



Material Content Data Sheet



Sales Product Name		BGT 24MR2 E6327		Issued		19. July 2018		
MA#		MA001091272						
Package		PG-VQFN-32-9		Weight*		55.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.627	2.93	2.93	29287	29287
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		146	
	non noble metal	zinc	7440-66-6	0.032	0.06		583	
	non noble metal	iron	7439-89-6	0.647	1.17		11656	
wire	non noble metal	copper	7440-50-8	26.284	47.33	48.57	473268	485653
	noble metal	gold	7440-57-5	0.476	0.86	0.86	8570	8570
	encapsulation	organic material	carbon black	1333-86-4	0.072	0.13		1293
encapsulation	plastics	epoxy resin	-	3.040	5.47		54736	
	inorganic material	silicondioxide	60676-86-0	20.824	37.50	43.10	374965	430994
leadfinish	non noble metal	tin	7440-31-5	1.435	2.58	2.58	25842	25842
plating	noble metal	silver	7440-22-4	0.555	1.00	1.00	9993	9993
glue	plastics	epoxy resin	-	0.123	0.22		2222	
	noble metal	silver	7440-22-4	0.413	0.74	0.96	7439	9661
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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